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## BIB DATA SHEET

CONFIRMATION NO. 1053

SERIAL NUMBER	FILING or 371(c) DATE	CLASS	GROUP ART UNIT	ATTORNEY DOCKET NO.		
10/550,153	09/20/2005	438	2823	038915.45		
<b>RULE</b>						
<b>APPLICANTS</b> Toshikazu Okubo, Tokyo, JAPAN; Katsuyoshi Naoi, Tokyo, JAPAN; Yuka Yamada, Tokyo, JAPAN;						
<b>** CONTINUING DATA *****</b> This application is a 371 of PCT/JP04/03934 03/23/2004      Yes /K.N./						
<b>** FOREIGN APPLICATIONS *****</b> Yes /K.N./ JAPAN 2003-082037 03/25/2003 JAPAN 2003-350544 10/09/2003						
<b>** IF REQUIRED, FOREIGN FILING LICENSE GRANTED **</b> 05/11/2006						
Foreign Priority claimed <input checked="" type="checkbox"/> Yes <input type="checkbox"/> No 35 USC 119(a-d) conditions met <input checked="" type="checkbox"/> Yes <input type="checkbox"/> No Verified and Acknowledged <u>/KHIEM D NGUYEN/</u> Examiner's Signature		<input type="checkbox"/> Met after Allowance <u>/K.N./</u> Initials	<b>STATE OR COUNTRY</b> JAPAN	<b>SHEETS DRAWINGS</b> 9	<b>TOTAL CLAIMS</b> 21	<b>INDEPENDENT CLAIMS</b> 4
<b>ADDRESS</b> SQUIRE, SANDERS & DEMPSEY L.L.P. 1 MARITIME PLAZA, SUITE 300 SAN FRANCISCO, CA 94111 UNITED STATES						
<b>TITLE</b> Method for analyzing electrolytic copper plating solution, and analyzing device therefor and production method for semi-conductor product						
<b>FILING FEE RECEIVED</b> 1150	FEES: Authority has been given in Paper No. _____ to charge/credit DEPOSIT ACCOUNT No. _____ for following:			<input type="checkbox"/> All Fees <input type="checkbox"/> 1.16 Fees (Filing) <input type="checkbox"/> 1.17 Fees (Processing Ext. of time) <input type="checkbox"/> 1.18 Fees (Issue) <input type="checkbox"/> Other _____ <input type="checkbox"/> Credit		